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(54) Title: CURABLE COMPOSITION AND METHOD

(57) Abstract: A curable resin composition useful for encapsulating solid state devices is describe The composition includes an epoxy resin, a poly(arylene ether) resin, a latent cationi cure catalyst effective to cure the epoxy resin, and about 70 to about 95 weight perce of an inorganic filler, based on the total weight of the curable composition. A metho of encapsulating a solid state device with the composition and encapsulated device prepared with the composition are also described.

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